NUMBER C-174650

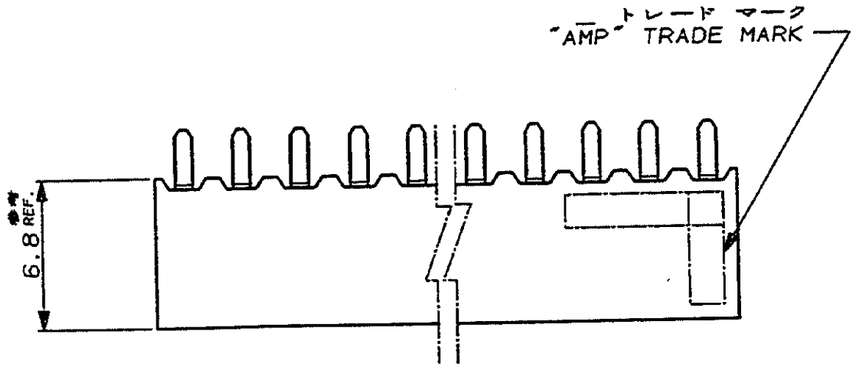
3rd ANGLE PROJECTION

METRIC

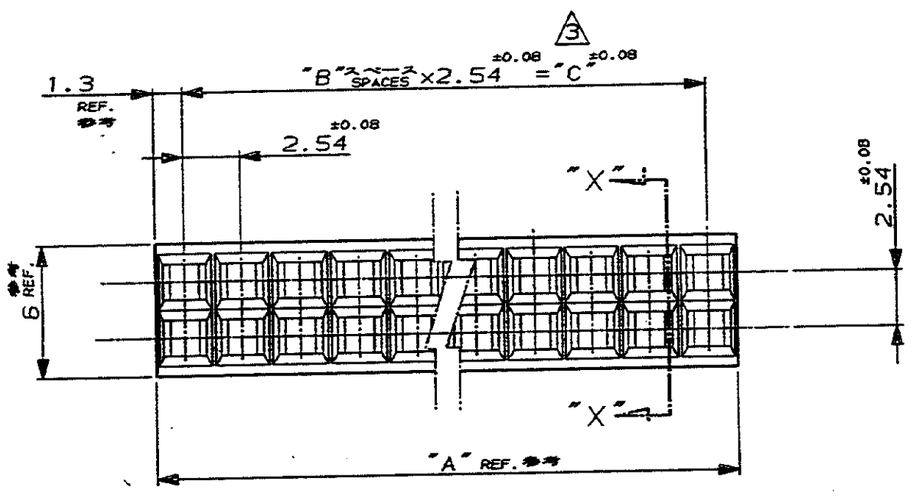
PROJ 651-106

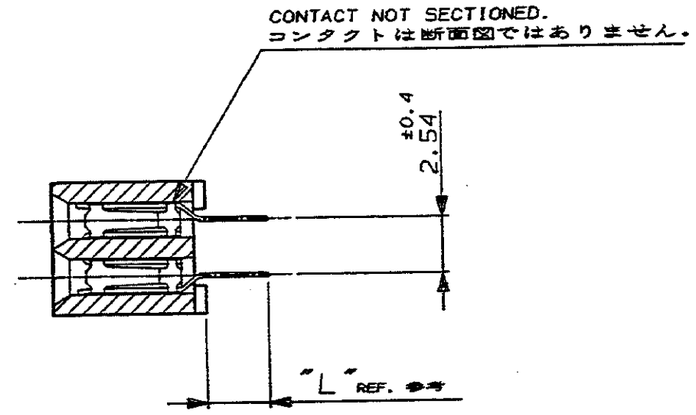
DIMENSIONS IN MILLIMETERS. DO NOT SCALE PRINT

PRINT DIST

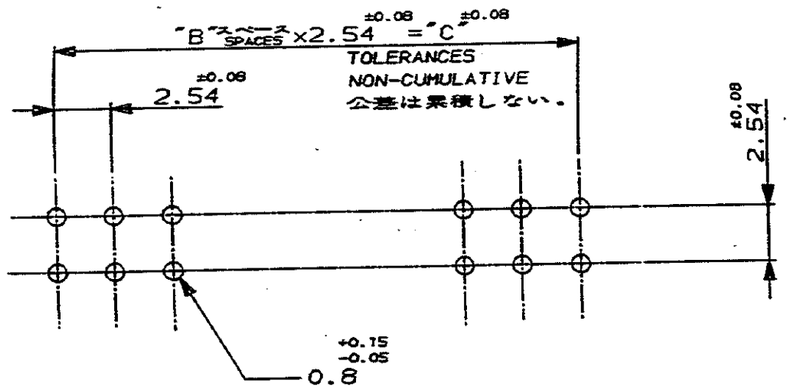


推奨基板厚 RECOMMENDED P.C.BOARD THK	"C" ±0.08	"B" スペース SPACES	"A" 参考 REF	"T" 金めっき厚 AU THK	"L" 参考 REF	極数 POS	型番 P/N
1.6±0.1	15.24	6	17.8		2.6	14	7- -3
0.3 MAX					1.2	24	7- -2
1.6±0.1	27.94	11	30.5		2.6	24	7- -1
0.3 MAX					1.2	26	7- -0
	30.48	12	33.0	0.0001AVE		26	6-174650-9





断面 "X"-"X"
SECT "X"-"X"



プリント基板推奨取付穴位置
RECOMMENDED HOLE LAYOUT

1.6±0.1					2.6		6-174650-8
0.3 MAX	15.24	6	17.8	0.00076MIN	1.2	14	6- -7
				0.00076MIN			6- -6
				0.0002MIN			6- -5
1.6±0.1				0.0001AVE	2.6		6- -4
				0.00076MIN			6- -3
				0.0002MIN			6- -2
0.3 MAX	10.16	4	12.7	0.0001AVE	1.2	10	6- -1
1.6±0.1	48.26	19	50.8	0.00076MIN	2.6	40	6- -0
	43.18	17	45.7			36	5- -9
	40.64	16	43.2			34	5- -8
	25.40	10	27.9			22	5- -7
	22.86	9	25.4			20	5- -6
	17.78	7	20.3			16	5- -5
	7.62	3	10.2			8	5- -4
	5.08	2	7.6			6	5- -3
	2.54	1	5.1			4	5- -2
	〃	〃	2.5	0.00076MIN		2	5- -1
	48.26	19	50.8	0.0002MIN		40	5- -0
	43.18	17	45.7			36	4- -9
	40.64	16	43.2			34	4- -8
	25.40	10	27.9			22	4- -7
	22.86	9	25.4			20	4- -6
	17.78	7	20.3			16	4- -5
	7.62	3	10.2			8	4- -4
	5.08	2	7.6			6	4- -3
	2.54	1	5.1			4	4- -2
	〃	〃	2.5	0.0002MIN		2	4- -1
	48.26	19	50.8	0.0001AVE		40	4- -0
	43.18	17	45.7			36	3- -9
	40.64	16	43.2			34	3- -8
	25.40	10	27.9			22	3- -7
	22.86	9	25.4			20	3- -6
	17.78	7	20.3			16	3- -5
	7.62	3	10.2			8	3- -4
	5.08	2	7.6			6	3- -3
	2.54	1	5.1			4	3- -2
1.6±0.1	〃	〃	2.5	0.0001AVE	2.6	2	3- -1
0.3 MAX	48.26	19	50.8	0.00076MIN	1.2	40	3- -0
	43.18	17	45.7			36	2- -9
	40.64	16	43.2			34	2- -8
	25.40	10	27.9			22	2- -7
	22.86	9	25.4			20	2- -6
	17.78	7	20.3			16	2- -5
	7.62	3	10.2			8	2- -4
	5.08	2	7.6			6	2- -3
	2.54	1	5.1			4	2- -2
	〃	〃	2.5	0.00076MIN		2	2- -1
	48.26	19	50.8	0.0002MIN		40	2- -0
	43.18	17	45.7			36	1- -9
	40.64	16	43.2			34	1- -8
	25.40	10	27.9			22	1- -7
	22.86	9	25.4			20	1- -6
	17.78	7	20.3			16	1- -5
	7.62	3	10.2			8	1- -4
	5.08	2	7.6			6	1- -3
	2.54	1	5.1			4	1- -2
	〃	〃	2.5	0.0002MIN		2	1- -1
	48.26	19	50.8	0.0001AVE		40	1- -0
	43.18	17	45.7			36	-9
	40.64	16	43.2			34	-8
	25.40	10	27.9			22	-7
	22.86	9	25.4			20	-6
	17.78	7	20.3			16	-5
	7.62	3	10.2			8	-4
	5.08	2	7.6			6	-3
	2.54	1	5.1			4	-2
0.3 MAX	〃	〃	2.5	0.0001AVE	1.2	2	174650-1
推奨基板厚 RECOMMENDED P.C.BOARD THK	"C" ±0.08	"B" スペース SPACES	"A" 参考 REF	"T" 金めっき厚 AU THK	"L" 参考 REF	極数 POS	型番 P/N

NOTES;

1. MATERIAL; HOUSING: THERMOPLASTIC UL94V-0
   RECEPTACLE CONTACT: PHOSPHOR BRONZE.
2. FINISH; CONTACT POINT: "T" THK GOLD ON NICKEL
   0.0013 MIN ALL OVER.
   SOLDERING AREA: 0.001 MIN TIN-LEAD.
3. THESE DIMENSIONS APPLY TO CAVITY CENTER LINES ONLY, NOT CONTACT LOCATIONS. (TOLERANCES NON-CUMULATIVE)
4. PRODUCT SPEC: 108-5245
   APPLICATION SPEC: 114-25018

注記;

1. 材料; ハウジング: 熱可塑性ポリエステル樹脂. 94V-0
   リセプタクル コンタクト: 燐青銅
2. 仕上げ; 接点部: "T" 厚の金めっき. NI下地 0.0013MIN.
   半田付部: 半田めっき 0.001MIN.
3. これらの寸法は、コンタクトの中心ではなく
   ハウジング穴の中心線で測定する.
   (公差は累積しない)
4. 製品規格; 108-5245
   取付適用規格; 114-25018

LTR	REVISION RECORD	DR	CHK	DATE
A4	REVISED ECN No. J-1127	I.E	YY	13-MAR-'90
A3	ADDED NEW P/N ECN No. J-12650	I.E	S.M	9-NOV-'90
A2	ADDED NEW P/N ECN No. J-12582	I.E	S.M	23-JUL-'90
A1	ADDED NEW P/N ECN No. J-12586	I.E	S.M	7-AUG-'90
A	REVISED ECN No. J-12016	I.E	S.M	1-AUG-'89
O3	ADDED NEW P/N ECN No. J-10602	I.E	S.M	29-MAR-'88
O2	ADDED NEW P/N ECN No. J-10515	I.E	S.M	23-JAN-'88
O1	ADDED NEW P/N ECN No. J-10338	I.E	S.M	17-NOV-'87
O	RELEASED ECN No. J-9990	I.E	H.T	2-SEP-'87

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WIRE RANGE	— mm² (AWG -)
INSULATION DIA	— mm
MATERIAL	注記参照 ⚠1 SEE NOTE ⚠1
FINISH	注記参照 ⚠2 SEE NOTE ⚠2
DR.	2-SEP-'87 I. ENOMOTO
DE.	2-SEP-'87 H. TAGUCHI
CHK.	1-FEB-'88 H. TAGUCHI
APP.	2-SEP-'87 H. TAGUCHI

NAME エコノミー アンプモジュ リセプタクル コネクター, 垂直取付型 タイン列間 2.54タイプ
ECONOMY AMPMODU RECE CONN, 2.45 TINE WIDTH, V-TYPE

GENERAL TOLERANCE
0<dec 10 : ±0.2
10<dec 30 : ±0.25
30<dec 100 : ±0.3
ANGLES : ±3°

SIZE	LOC	NUMBER
C	J	C-174650

SCALE	REV.	SHEET
4-1	A4	1 OF 1

CUSTOMER DRAWING

AMP-J REV. 10/'89